

A Product Line of Diodes Incorporated



SPECIFICATION FOR APPROVAL

CUSTOMER

NOMINAL FREQUENCY

25.00000 MHz

TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL

FL2500333Q

SPEC. NO. (P/N)

PRODUCT TYPE

CUSTOMER P/N

ISSUE DATE

VERSION

В

November 26, 2017

APPROVED	PREPARED	QA	
Brenda	Claine	Dong Jang	

Diodes Incorporated

No.2, Ziqiang 5th Rd., Zhongli Industrial Park, Zhongli Dist., Taoyuan City 32063, Taiwan (R.O.C.) TEL: 886-3-451-8888 FAX: 886-3-461-3865 https://www.diodes.com

- *Pb-free
- *RoHS Compliant
- *HF-Halogen Free
- *REACH Compliant
- *AEC-Q200 Compliant

FL2500333Q

VER. B 26-Nov-17

VERSION HISTORY

Version No.	Version Date	Description	Notes
A	Feb.25,2016	Initial Release	
В	Nov.26,2017	Updated logo	



FL2500333Q

VER. B 26-Nov-17

ELECTRICAL SPECIFICATIONS

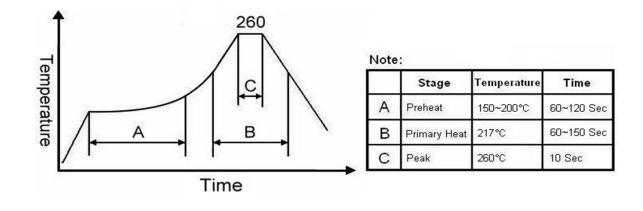
ltem	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	25.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	18	pF	
Calibration Tolerance	FL	±20	ppm	at 25°C±3°C
Operating Temperature Range	TR	-40 to +85	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±20	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		300	μW	
Equivalent Series Resistance	ESR	30	Ω	Мах
Shunt Capacitance	C0	5	pF	Мах
Aging at 25°C		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	MΩ	Min

X This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).

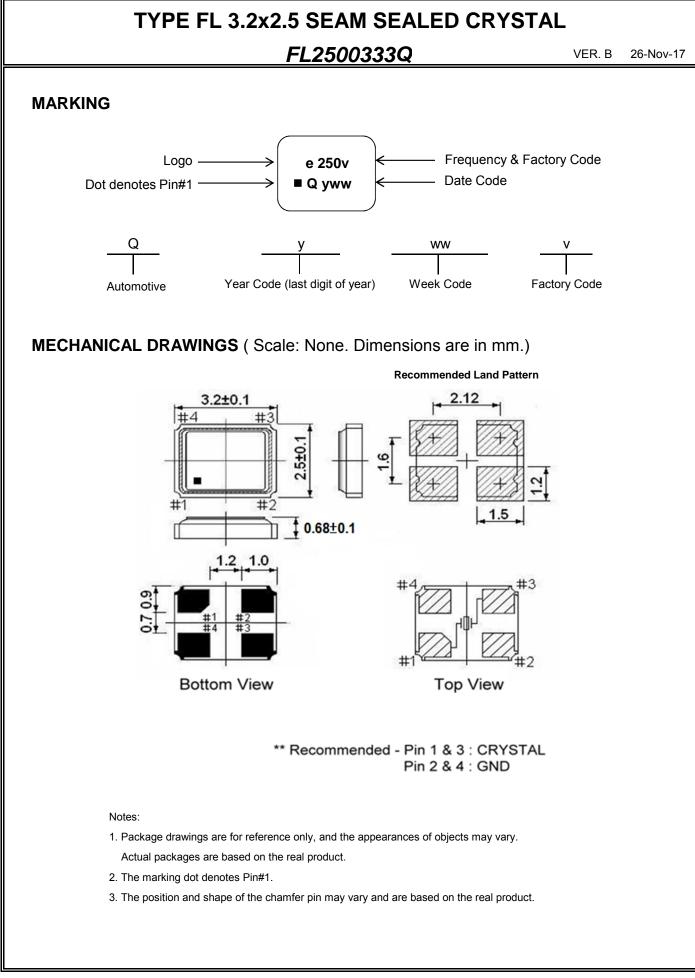


FL2500333Q

AEC-Q200 RELIABILITY TEST SPECIFICATIONS: 1. Initial 1.1 Physical Dimensions: JESD22, Method JB1-100 1.2 External Visual: MIL-STD-883, Method 2009 1.3 Freq. Vs. Temperature: Per Specification/Datasheet 2. Mechanical 2.1 Mechanical Shock: MIL-STD-202 Method 213 2.2 Vibration: MIL-STD-202 Method 204 2.3 Solderability: J-STD-002 2.4 Board Flex: AEC Q200-005 2.5 Terminal Strength (SMD): AEC Q200-006 3.Environmental 3.1 Temp Cycle: JESD22, Method JA-104 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210 3.3 High Temperature Operating Life: MIL-STD-202, Method 108 3.4 High Temp Exposure: MIL-STD-202, Method 108 3.5 High Temp & High Humidity: MIL-STD-202, Method 103 3.6 Thermal Shock: MIL-STD-202, Method 107 SUGGESTED IR REFLOW PROFILE *As per IPC-JEDEC J-STD-020D





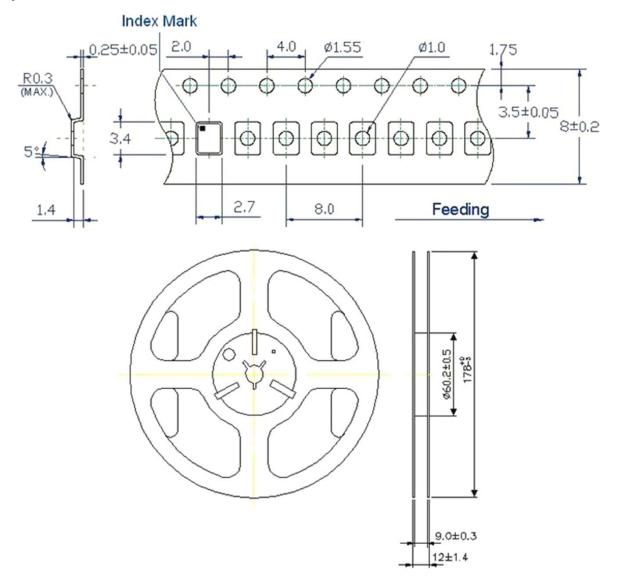




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Tape & Reel



- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.



